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Vishay Semiconductors

COMPLIANT

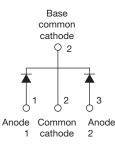
HALOGEN FREE

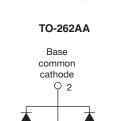
Ultrafast Rectifier, 2 x 5 A FRED Pt®





TO-263AB (D²PAK)





VS-MURB1020CTHM3

1 cathode 2
VS-MURB1020CT-1HM3

Anode

Anode Common

| PRODUCT SUMMARY | |
|----------------------------------|---|
| Package | TO-263AB (D ² PAK), TO-262AA |
| I _{F(AV)} | 2 x 5 A |
| V_{R} | 200 V |
| V _F at I _F | 0.87 |
| t _{rr} (typ.) | 19 ns |
| T _J max. | 175 °C |
| Diode variation | Common cathode |

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Meets JESD 201 class 1 whisker test
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

| ABSOLUTE MAXIMUM RATINGS | | | | | | | | | |
|---|-----------------------------------|---|-------------|-------|--|--|--|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS | | | | | |
| Peak repetitive reverse voltage | V _{RRM} | | 200 | V | | | | | |
| Average rectified forward current per le | | | 5 | ^ | | | | | |
| total device | e I _{F(AV)} | Rated V _R , T _C = 149 °C | 10 | | | | | | |
| Non-repetitive peak surge current per leg | I _{FSM} | | 50 | А | | | | | |
| Peak repetitive forward current per leg | I _{FM} | Rated V _R , square wave, 20 kHz, T _C = 149 °C | 10 | | | | | | |
| Operating junction and storage temperatures | T _J , T _{Stg} | | -65 to +175 | °C | | | | | |

| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | | | |
|--|-------------------------------------|--|------|------|------|-------|--|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | | | |
| Breakdown voltage, blocking voltage | V _{BR} , V _R | Ι _R = 100 μΑ | 200 | ı | - | | | | |
| Forward voltage | | I _F = 5 A, T _J = 25 °C | ı | 0.99 | 1.08 | V | | | |
| | V _F | I _F = 5 A, T _J = 125 °C | ı | 0.87 | 0.99 | | | | |
| Forward voltage | | I _F = 10 A, T _J = 25 °C | - | 1.12 | 1.25 | | | | |
| | | I _F = 10 A, T _J = 125 °C | - | 1.02 | 1.20 | | | | |
| Reverse leakage current | I _R | $V_R = V_R$ rated | - | - | 10 | | | | |
| neverse leakage current | | $T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$ | - | - | 250 | μΑ | | | |
| Junction capacitance | C _T | V _R = 200 V | ı | 8 | - | pF | | | |
| Series inductance | L _S | Measured lead to lead 5 mm from package body | ı | 8.0 | - | nH | | | |

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| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | | | |
|---|------------------|---|---|------|------|------|---------|--|--|
| PARAMETER | SYMBOL | TEST CO | NDITIONS | MIN. | TYP. | MAX. | UNITS | | |
| | | I _F = 1.0 A, dI _F /dt = 1 | 00 A/μs, V _R = 30 V | - | 19 | - | | | |
| Reverse recovery time | t _{rr} | T _J = 25 °C | | - | 24 | - | ns A nC | | |
| | | T _J = 125 °C | $I_F = 5 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 160 \text{ V}$ | - | 35 | - | | | |
| Deals was assent assument | I _{RRM} | T _J = 25 °C | | - | 3.3 | - | | | |
| Peak recovery current | | T _J = 125 °C | | - | 5.0 | - | | | |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C | | - | 33 | - | | | |
| | | T _J = 125 °C | | - | 76 | - | | | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | | | | |
|---|-----------------------------------|--|---|------|------------|------------------------|--|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | | | |
| Maximum junction and storage temperature range | T _J , T _{Stg} | | -65 | - | 175 | °C | | | |
| Thermal resistance, junction to case per leg | R _{thJC} | | - | - | 5 | | | | |
| Thermal resistance, junction to ambient per leg | R _{thJA} | | - | - | 50 | °C/W | | | |
| Thermal resistance, case to heatsink | R _{thCS} | Mounting surface, flat, smooth and greased | - | 0.5 | - | | | | |
| Maight | | | = | 2.0 | - | g | | | |
| Weight | | | - | 0.07 | - | oz. | | | |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) | | | |
| Marking davisa | | Case style TO-263AB (D ² PAK) | ase style TO-263AB (D ² PAK) MURB1020CTH | | | | | | |
| Marking device | | Case style TO-262AA | MURB1020CT-1H | | | | | | |

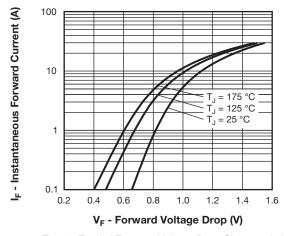


Fig. 1 - Typical Forward Voltage Drop Characteristics

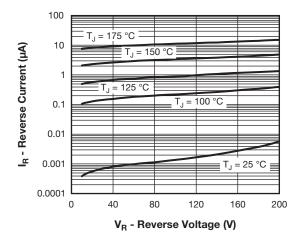


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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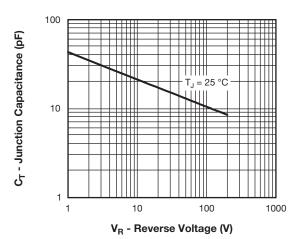


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

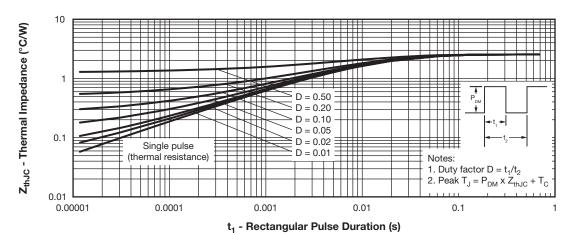


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

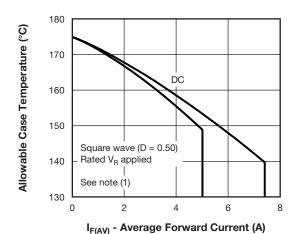


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

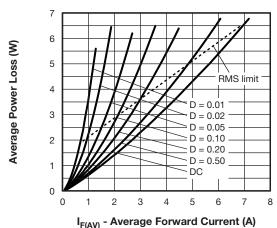


Fig. 6 - Forward Power Loss Characteristics

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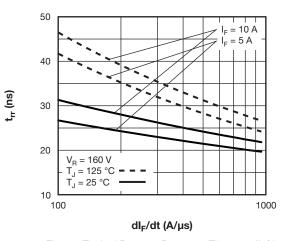


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

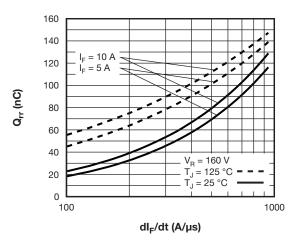
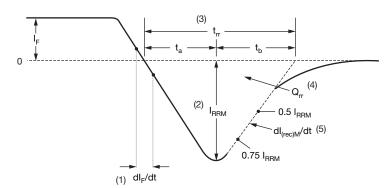


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{Rated } V_R \\ \end{array}$



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{r}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{BBM}

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

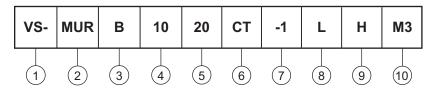
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Ultrafast MUR series

3 - B = $D^2PAK/TO-262$

4 - Current rating (10 = 10 A)

5 - Voltage rating (20 = 200 V)

6 - CT = center tap (dual)

7 - • None = D^2PAK

• -1 = TO-262

None = tube (50 pieces)

• L = tape and reel (left oriented, for D²PAK package)

• R = tape and reel (right oriented, for D²PAK package)

9 - H = AEC-Q101 qualified

10 - Environmental digit:

• M3 = halogen-free, RoHS-compliant, and terminations lead(Pb)-free

| ORDERING INFORMATION (Example) | | | | | | | | |
|--------------------------------|------------------|------------------------|-------------------------|--|--|--|--|--|
| PREFERRED P/N | QUANTITY PER T/R | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION | | | | | |
| VS-MURB1020CTHM3 | 50 | 1000 | Antistatic plastic tube | | | | | |
| VS-MURB1020CT-1HM3 | 50 | 1000 | Antistatic plastic tube | | | | | |
| VS-MURB1020CTLHM3 | 800 | 800 | 13" diameter reel | | | | | |
| VS-MURB1020CTRHM3 | 800 | 800 | 13" diameter reel | | | | | |

| LINKS TO RELATED DOCUMENTS | | | | | | |
|----------------------------|-------------------------------|--------------------------|--|--|--|--|
| Dimensions | TO-263AB (D ² PAK) | www.vishay.com/doc?95046 | | | | |
| Differsions | TO-262AA | www.vishay.com/doc?95419 | | | | |
| Part marking information | TO-263AB (D ² PAK) | www.vishay.com/doc?95444 | | | | |
| Part marking information | TO-262AA | www.vishay.com/doc?95443 | | | | |
| Packaging information | TO-263AB (D ² PAK) | www.vishay.com/doc?95032 | | | | |



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D²PAK

DIMENSIONS in millimeters and inches



| SYMBOL | MILLIMETERS | | INC | HES | NOTES | TES SYMBOL | | MILLIM | ETERS | INC | HES | NOTES |
|----------|-------------|-------|-------|-------|-------|------------|---------|--------|-------|-------|-------|-------|
| STIVIBUL | MIN. | MAX. | MIN. | MAX. | NOIES | NOTES | STWIDOL | MIN. | MAX. | MIN. | MAX. | NOTES |
| Α | 4.06 | 4.83 | 0.160 | 0.190 | | | D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 |
| A1 | 0.00 | 0.254 | 0.000 | 0.010 | | | Е | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | | E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | | е | 2.54 | BSC | 0.100 |) BSC | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | | Н | 14.61 | 15.88 | 0.575 | 0.625 | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | | L | 1.78 | 2.79 | 0.070 | 0.110 | |
| С | 0.38 | 0.74 | 0.015 | 0.029 | | | L1 | - | 1.65 | - | 0.066 | 3 |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | | L2 | 1.27 | 1.78 | 0.050 | 0.070 | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | | L3 | 0.25 | BSC | 0.010 | BSC | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | | L4 | 4.78 | 5.28 | 0.188 | 0.208 | |

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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TO-262

DIMENSIONS in millimeters and inches



| SYMBOL | MILLIM | IETERS | INC | INCHES | | |
|---------|--------|--------|-------|--------|-------|--|
| STWIDOL | MIN. | MAX. | MIN. | MAX. | NOTES | |
| Α | 4.06 | 4.83 | 0.160 | 0.190 | | |
| A1 | 2.03 | 3.02 | 0.080 | 0.119 | | |
| b | 0.51 | 0.99 | 0.020 | 0.039 | | |
| b1 | 0.51 | 0.89 | 0.020 | 0.035 | 4 | |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 | | |
| b3 | 1.14 | 1.73 | 0.045 | 0.068 | 4 | |
| С | 0.38 | 0.74 | 0.015 | 0.029 | | |
| c1 | 0.38 | 0.58 | 0.015 | 0.023 | 4 | |
| c2 | 1.14 | 1.65 | 0.045 | 0.065 | | |
| D | 8.51 | 9.65 | 0.335 | 0.380 | 2 | |
| D1 | 6.86 | 8.00 | 0.270 | 0.315 | 3 | |
| E | 9.65 | 10.67 | 0.380 | 0.420 | 2, 3 | |
| E1 | 7.90 | 8.80 | 0.311 | 0.346 | 3 | |
| е | 2.54 | BSC | 0.10 | D BSC | | |
| L | 13.46 | 14.10 | 0.530 | 0.555 | | |
| L1 | - | 1.65 | - | 0.065 | 3 | |
| L2 | 3.36 | 3.71 | 0.132 | 0.146 | | |

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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